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(12) **United States Design Patent**
Fitzsimmons, Jr. et al.

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(45) **Date of Patent: ** *Apr. 23, 2002**

(54) **HIP PACK FOR AN ELECTRONIC DEVICE**

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(73) Assignee: **Vulcan Northwest, Inc.**, Seattle, WA (US)

(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **14 Years**

(21) Appl. No.: **29/124,989**

(22) Filed: **Jun. 16, 2000**

(51) **LOC (7) Cl.** **03-01**

(52) **U.S. Cl.** **D3/218**

(58) **Field of Search** D3/218, 215, 224, D3/226, 228, 222, 223, 201, 232, 233; 224/901, 904, 240, 241, 268, 236

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Primary Examiner—Catherine R. Oliver
(74) *Attorney, Agent, or Firm*—Cooley Godward LLP

(57) **CLAIM**

The ornamental design for a hip pack for an electronic device, as shown and described.

DESCRIPTION

FIG. **1** is a bottom perspective view of a hip pack for an electronic device showing my new design;

FIG. **2** is a top perspective view thereof;

FIG. **3** is a front elevational view thereof;

FIG. **4** is a right side elevational view thereof;

FIG. **5** is a left side elevational view thereof;

FIG. **6** is a rear elevational view thereof;

FIG. **7** is a top plan view thereof;

FIG. **8** is a bottom plan view thereof;

FIG. **9** is a bottom perspective view of an alternate embodiment of the hip pack for an electronic device;

FIG. **10** is a top perspective view of FIG. **9**;

FIG. **11** is a front elevational view of FIG. **9**;

FIG. **12** is a right side elevational view of FIG. **9**;

FIG. **13** is a left side elevational view of FIG. **9**;

FIG. **14** is a rear elevational view of FIG. **9**;

FIG. **15** is a top plan view of FIG. **9**;

FIG. **16** is a bottom plan view of FIG. **9**;

FIG. **17** is a bottom perspective view of another alternative embodiment of the hip pack for an electronic device;

FIG. **18** is a top perspective view of FIG. **17**;

FIG. **19** is a front elevational view of FIG. **17**;

FIG. **20** is a right side elevational view of FIG. **17**;

FIG. **21** is a left side elevational view of FIG. **17**;

FIG. **22** is a rear elevational view of FIG. **17**;

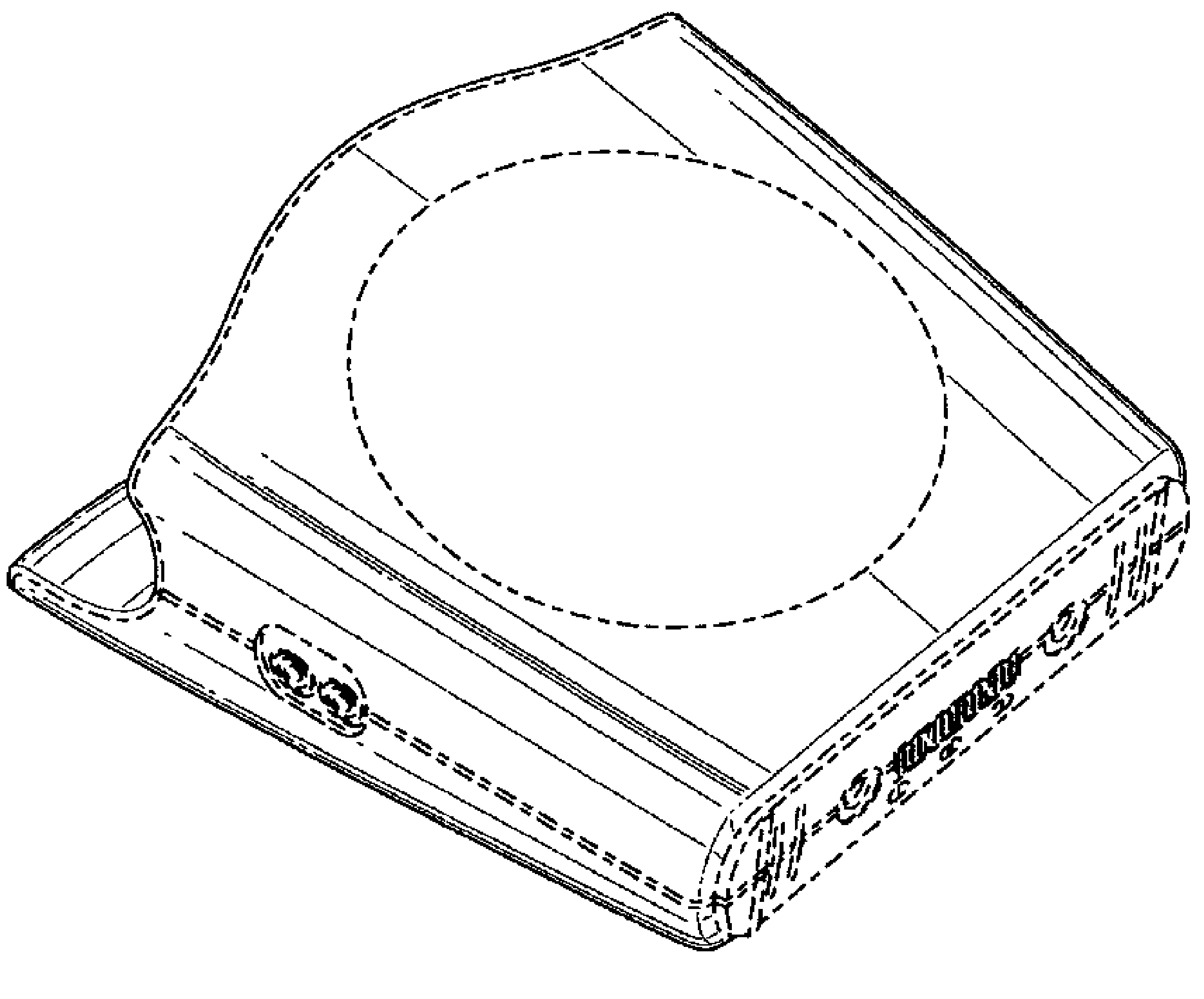
FIG. **23** is a top plan view of FIG. **17**;

FIG. **24** is a bottom plan view of FIG. **17**; and,

FIG. **25** is a left side perspective view of the hip pack for an electronic device illustrating its environment.

The broken line disclosure illustrates the environment for the hip pack for an electronic device only and forms no part of the claimed design.

1 Claim, 19 Drawing Sheets



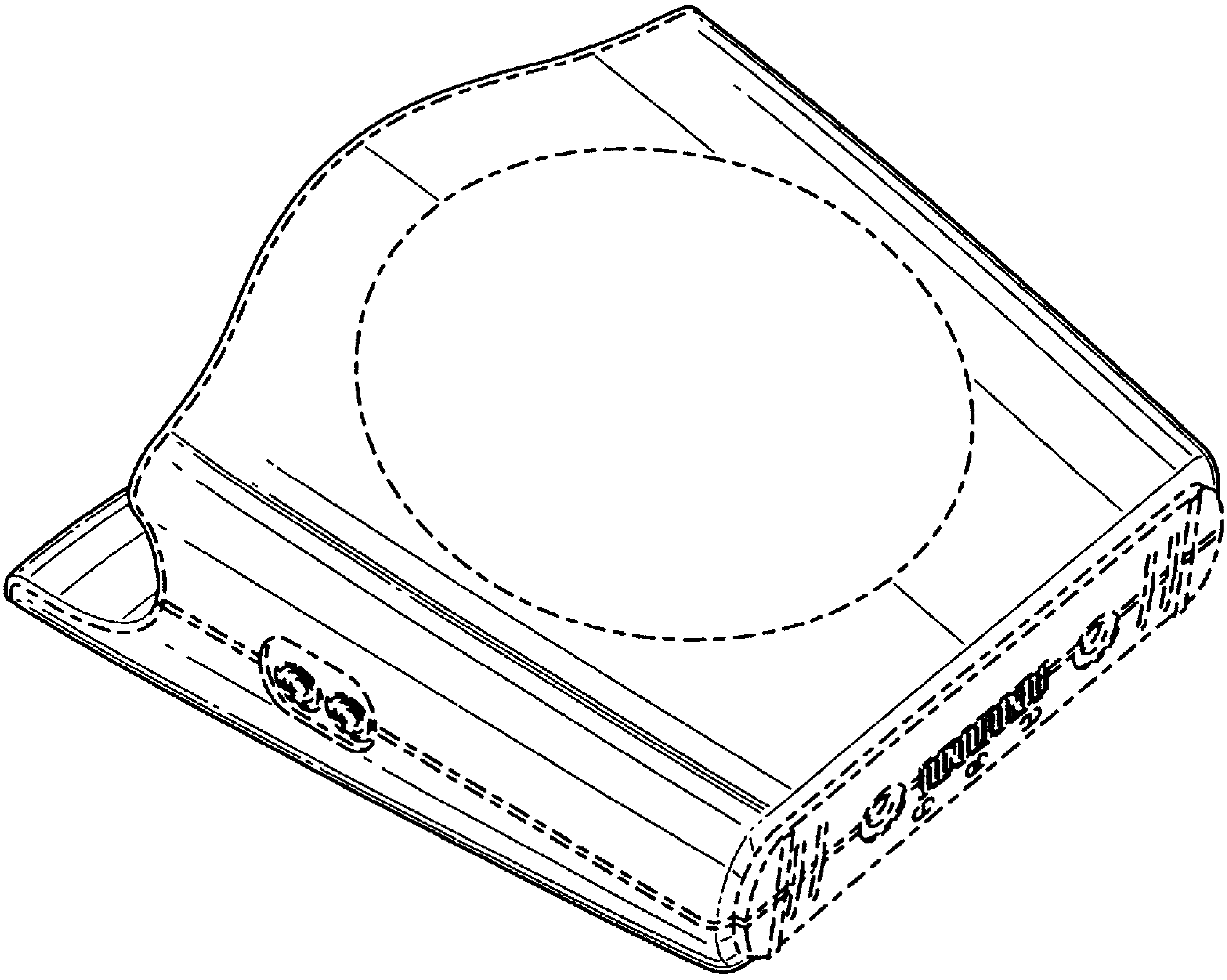


FIG. 1

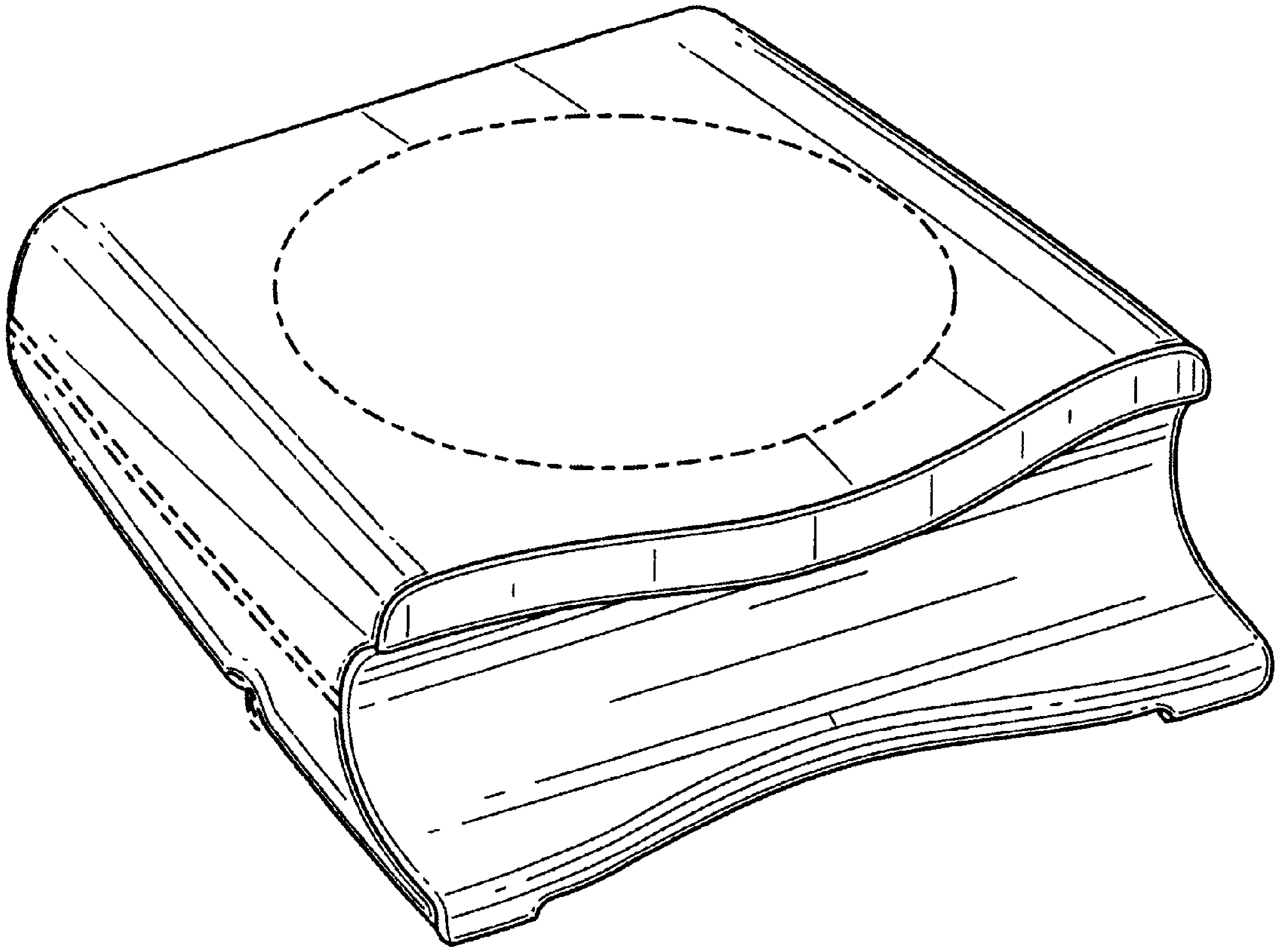


FIG. 2

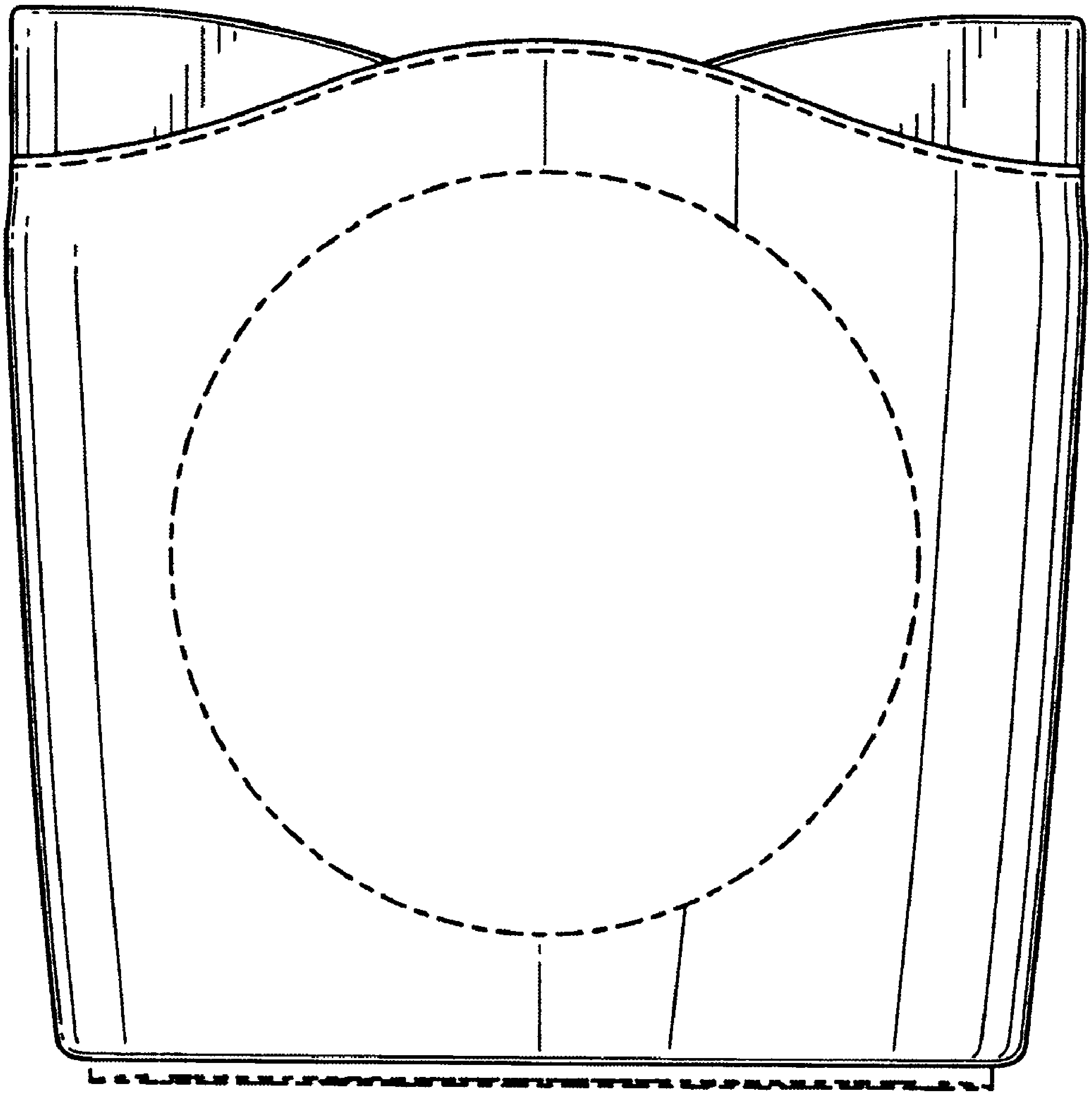


FIG. 3

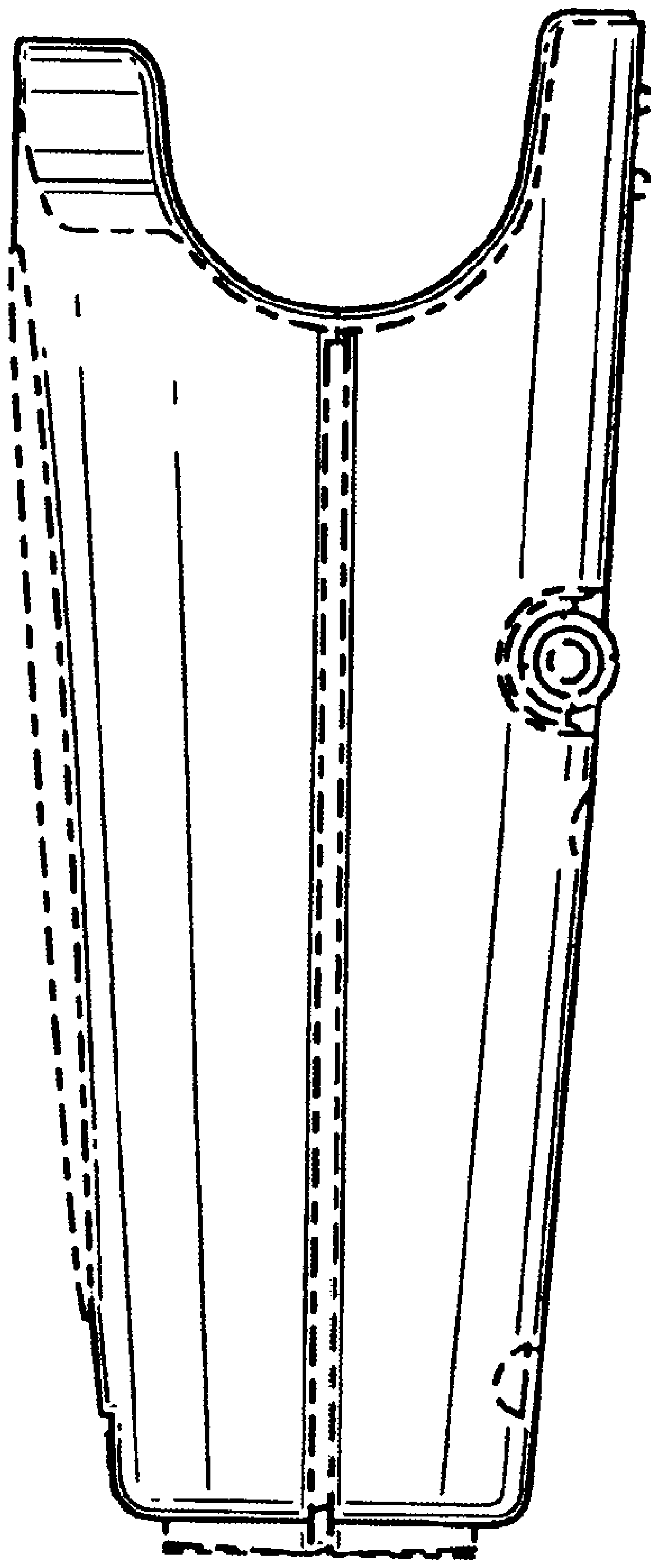
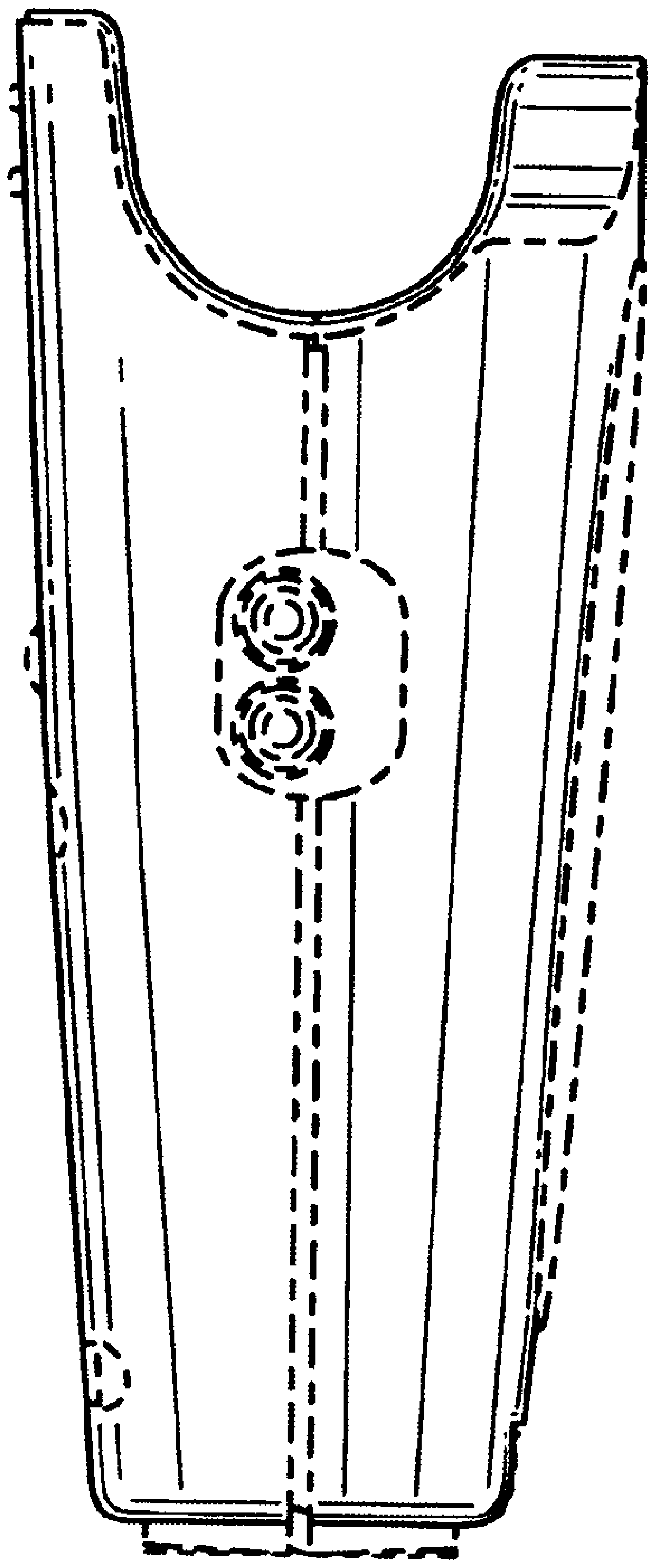


FIG. 4



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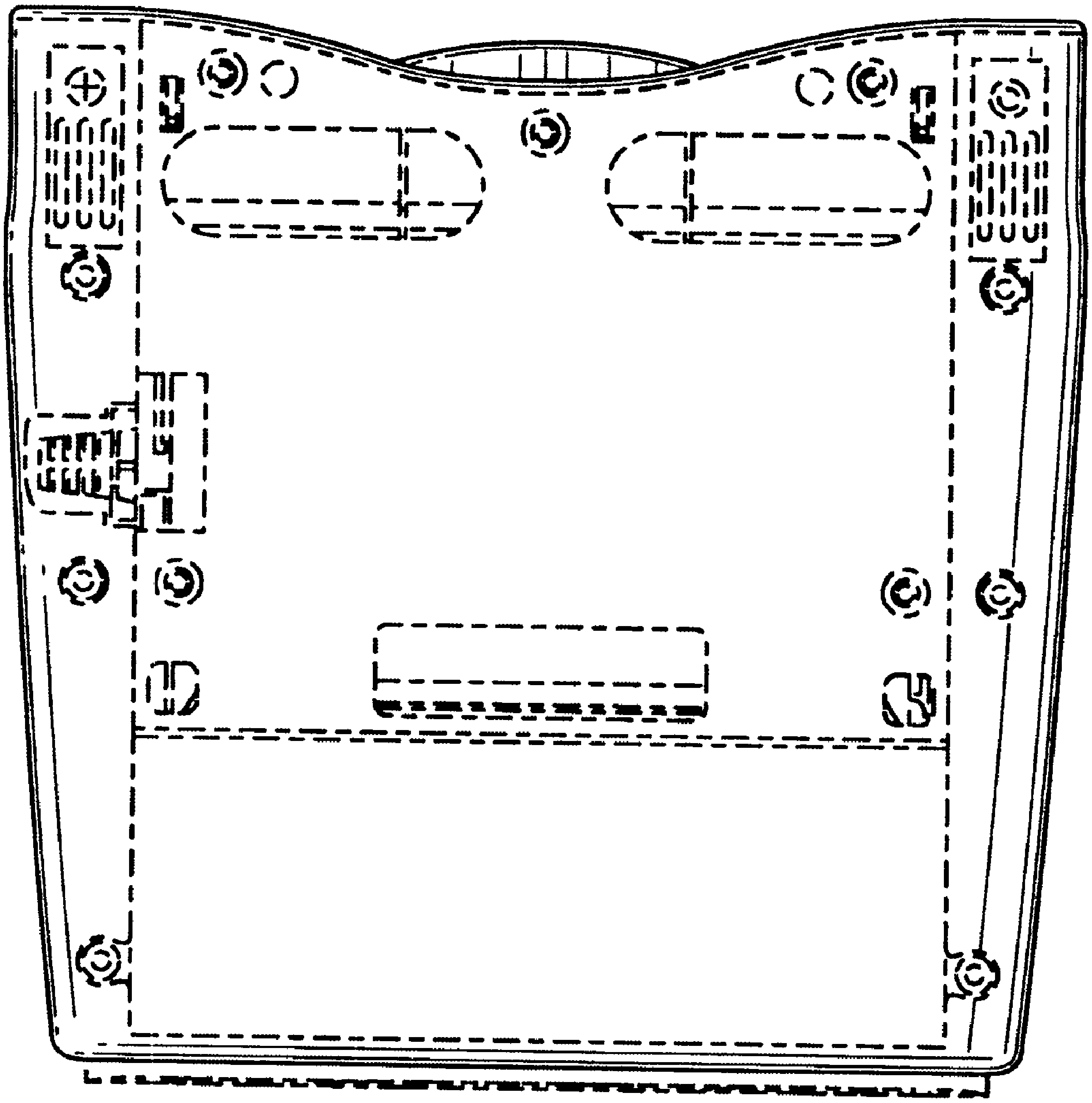


FIG. 6

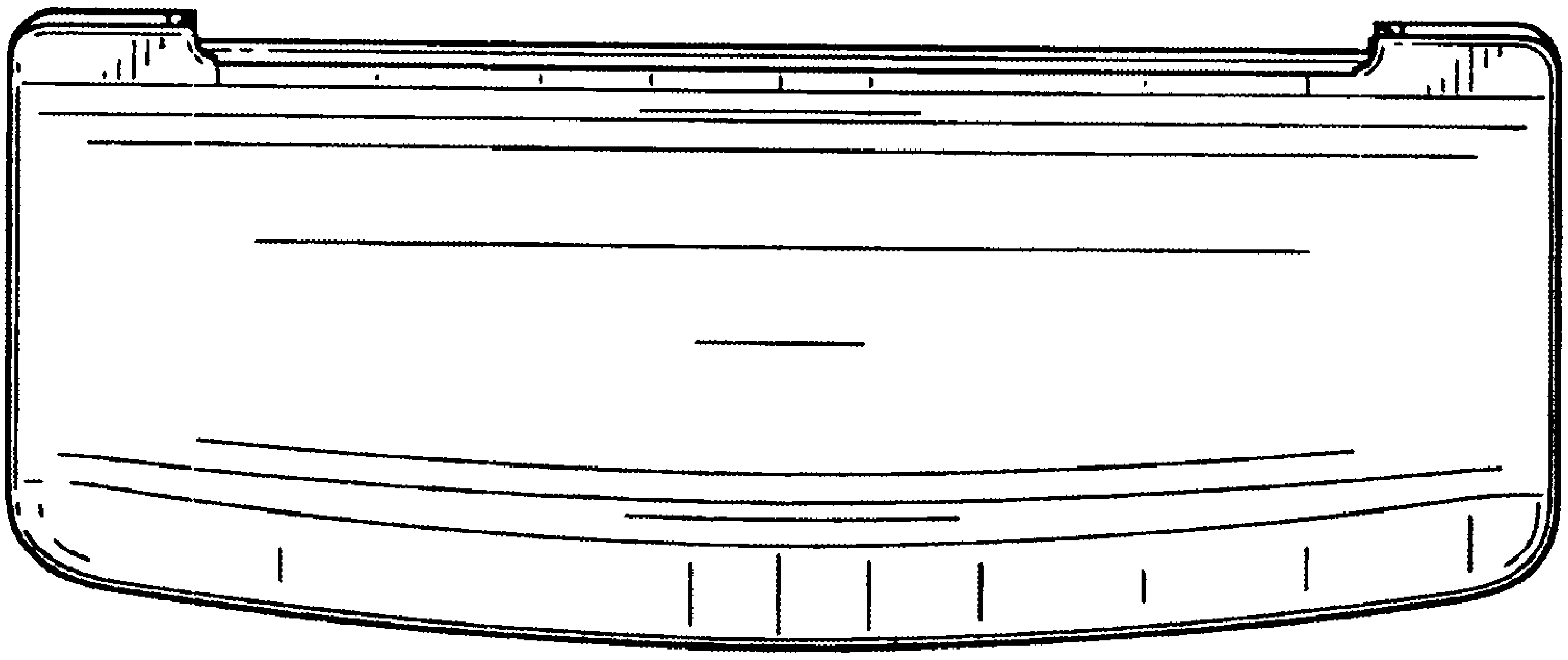


FIG. 7

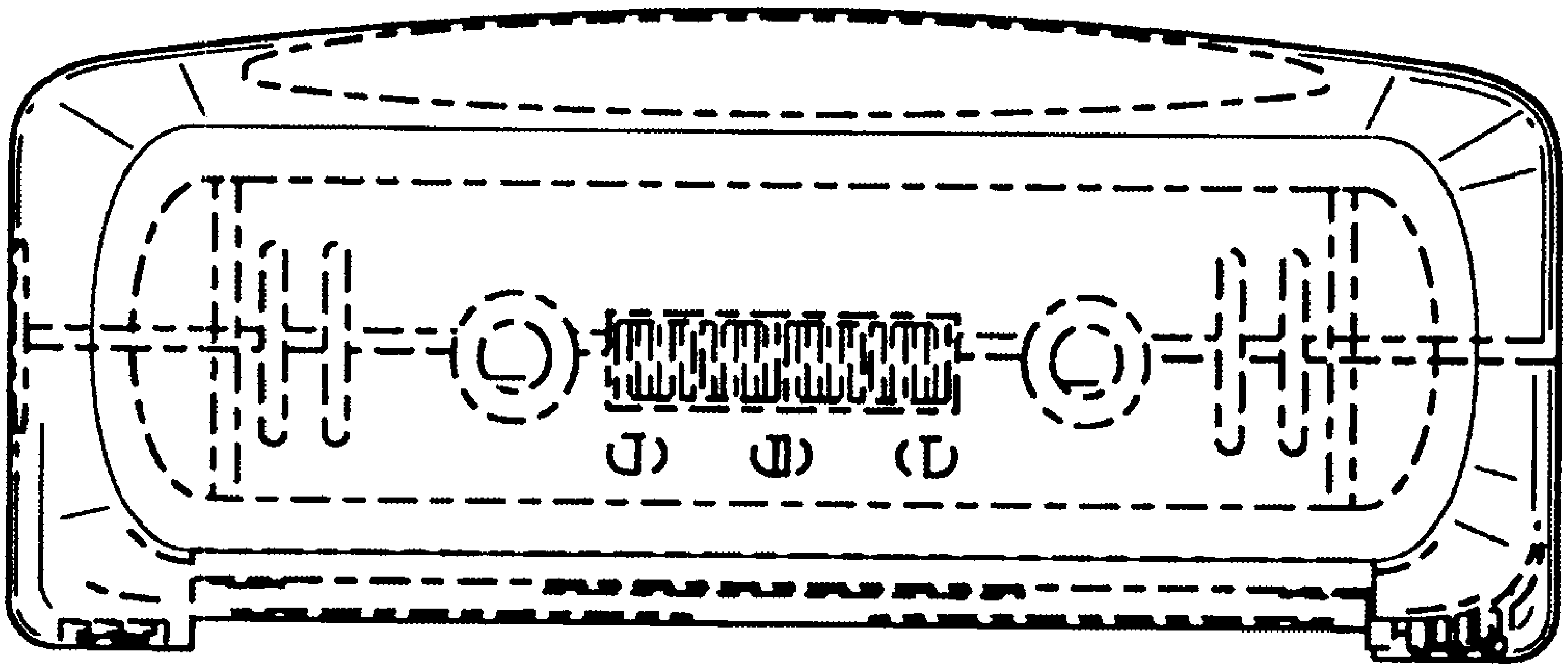


FIG. 8

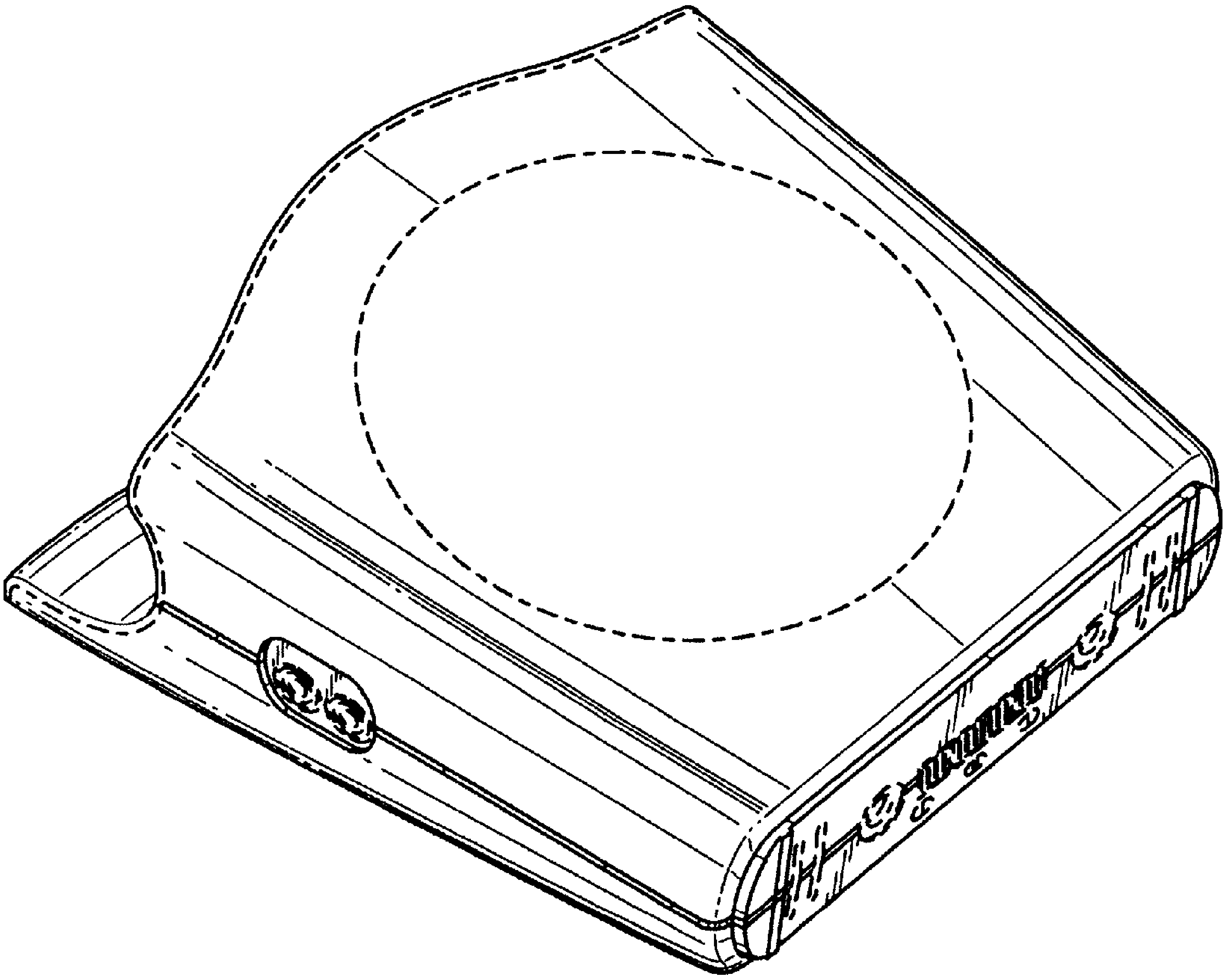


FIG. 9

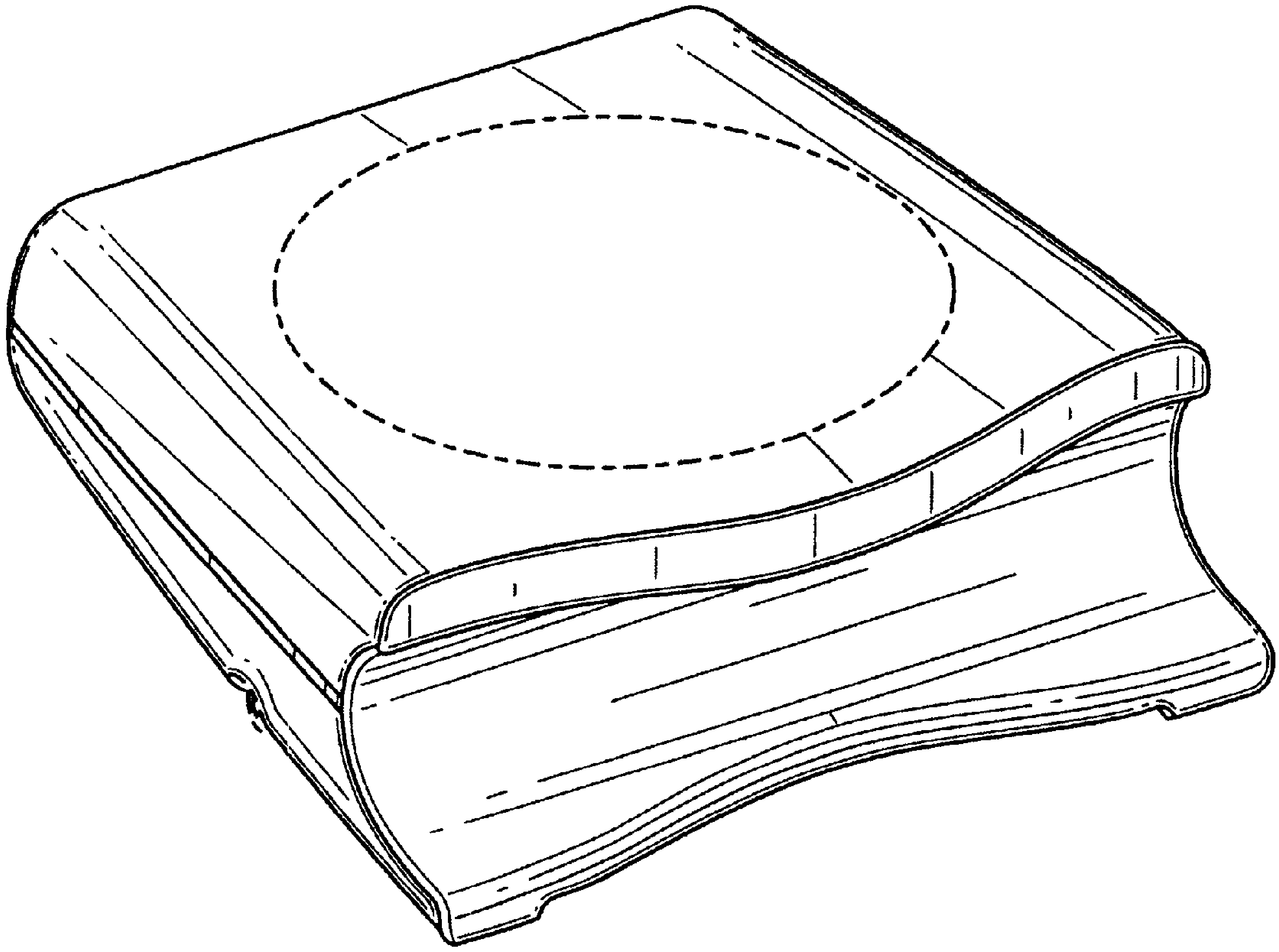


FIG. 10

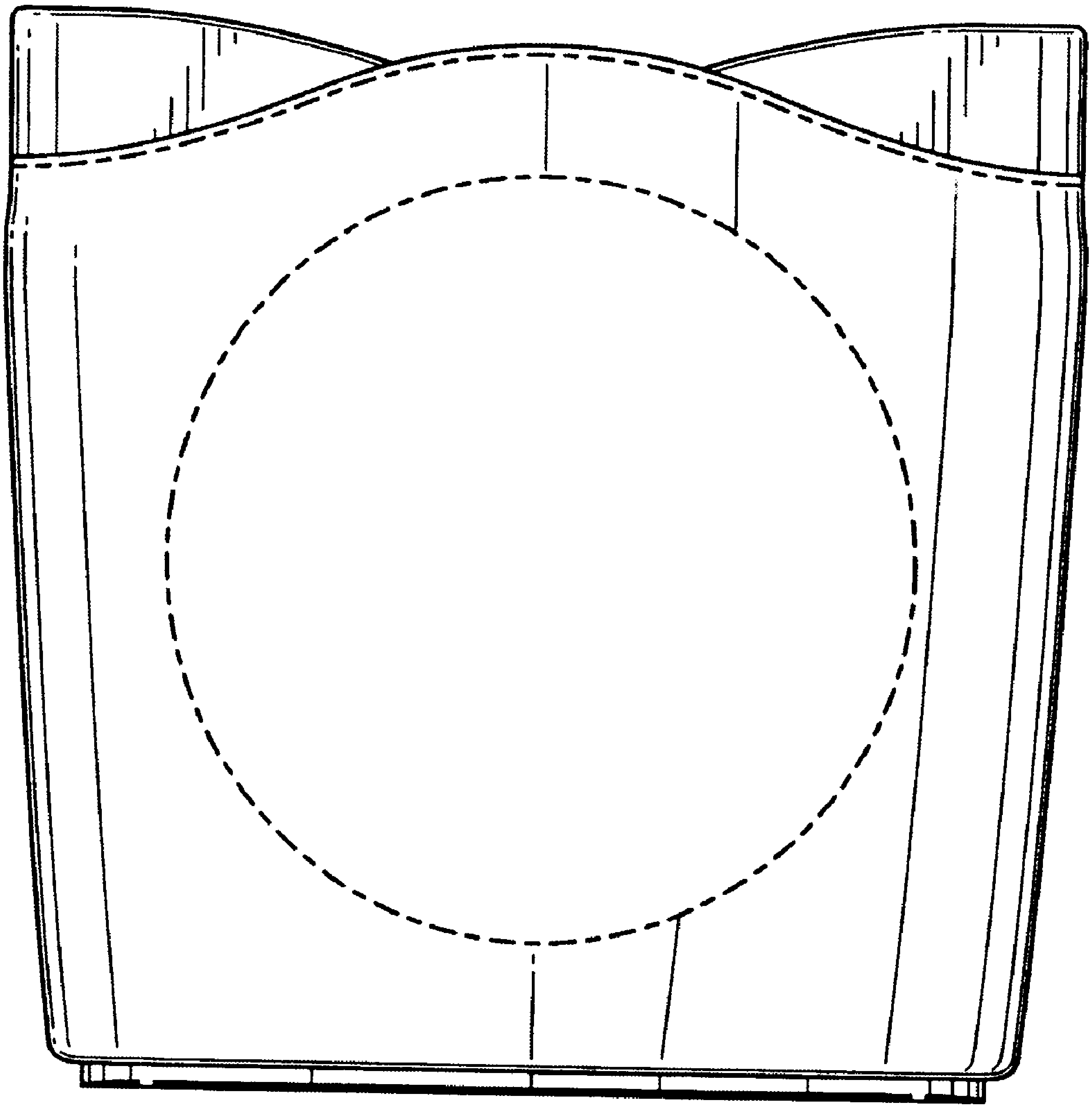


FIG. 11

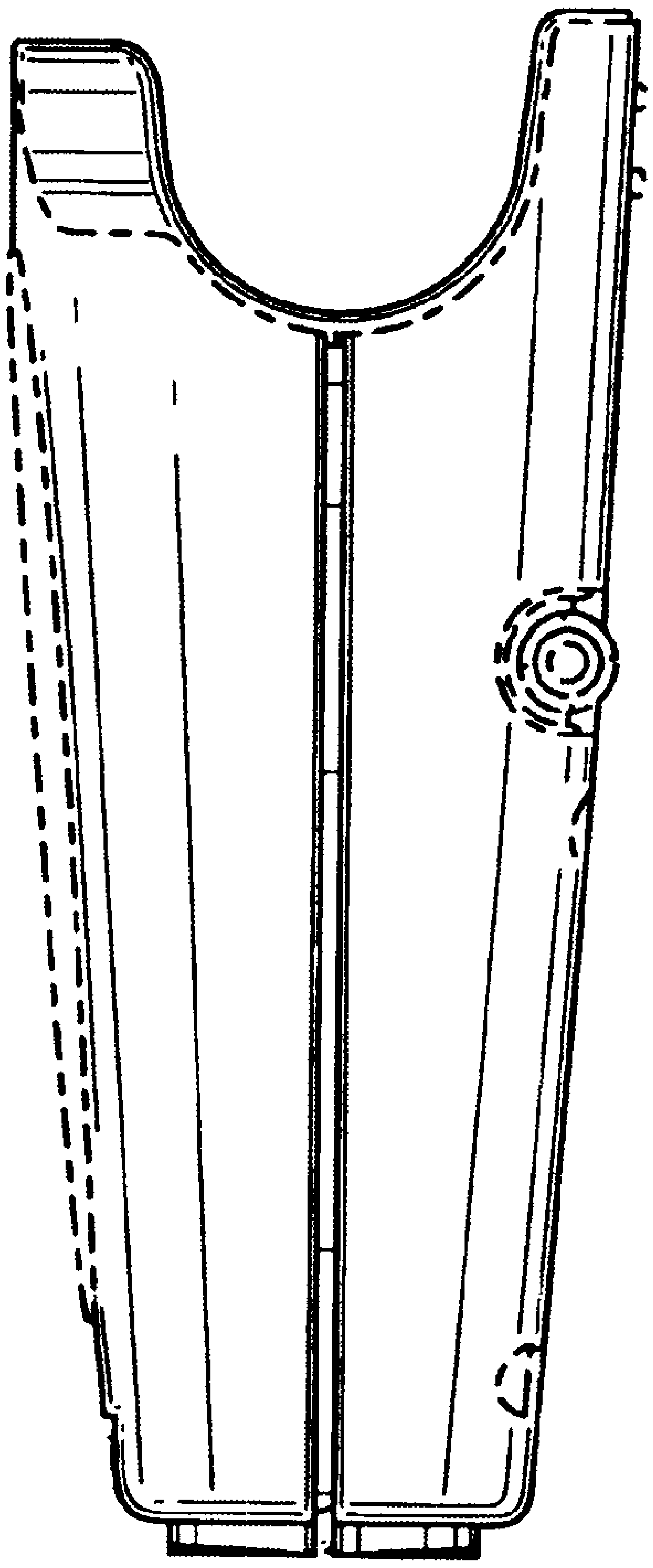


FIG. 12

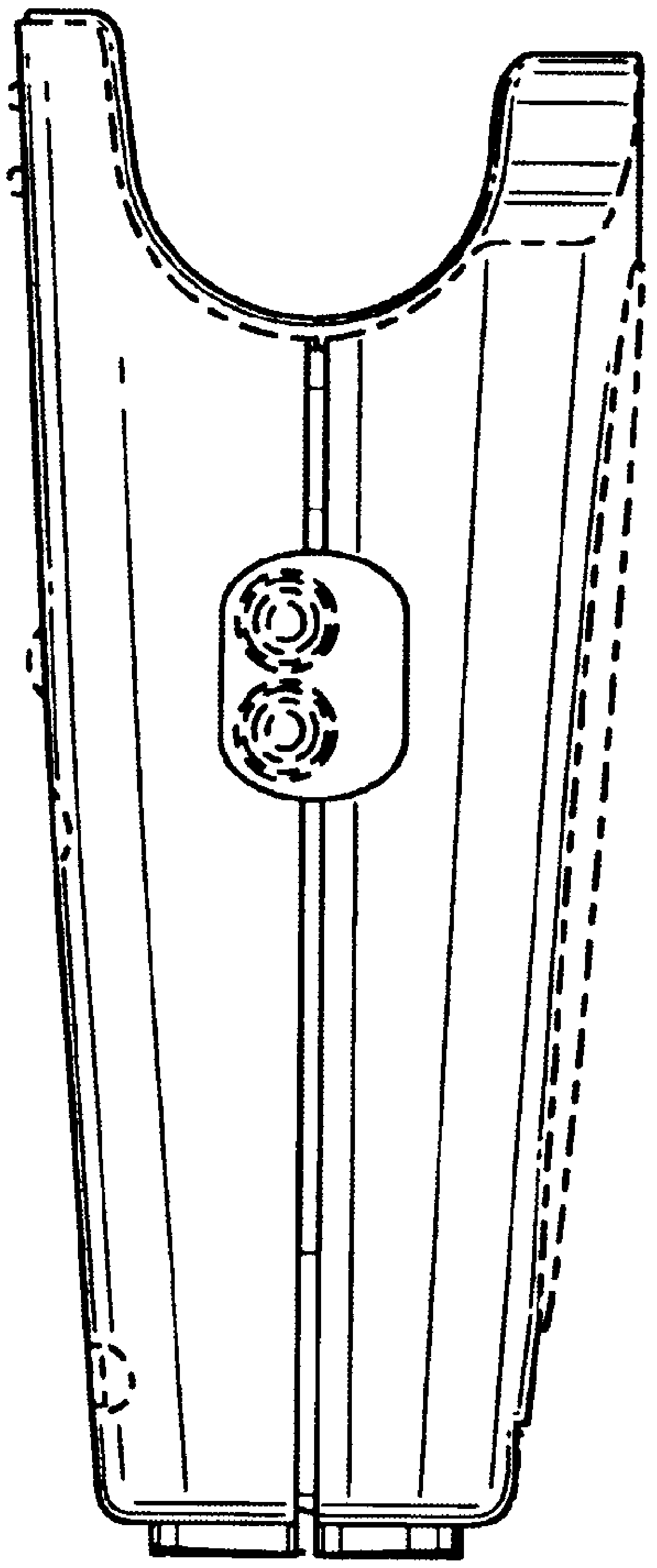


FIG. 13

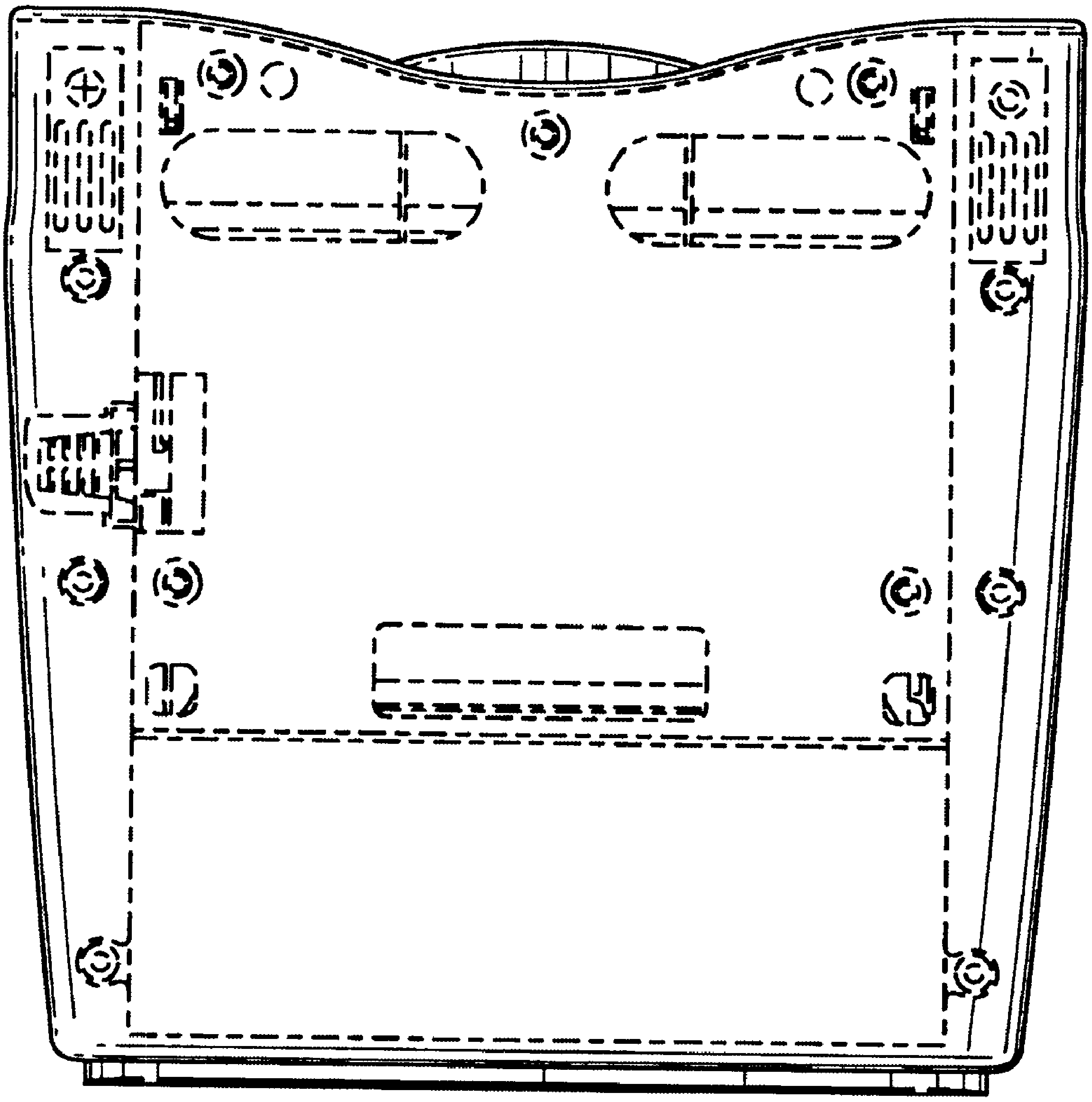


FIG. 14

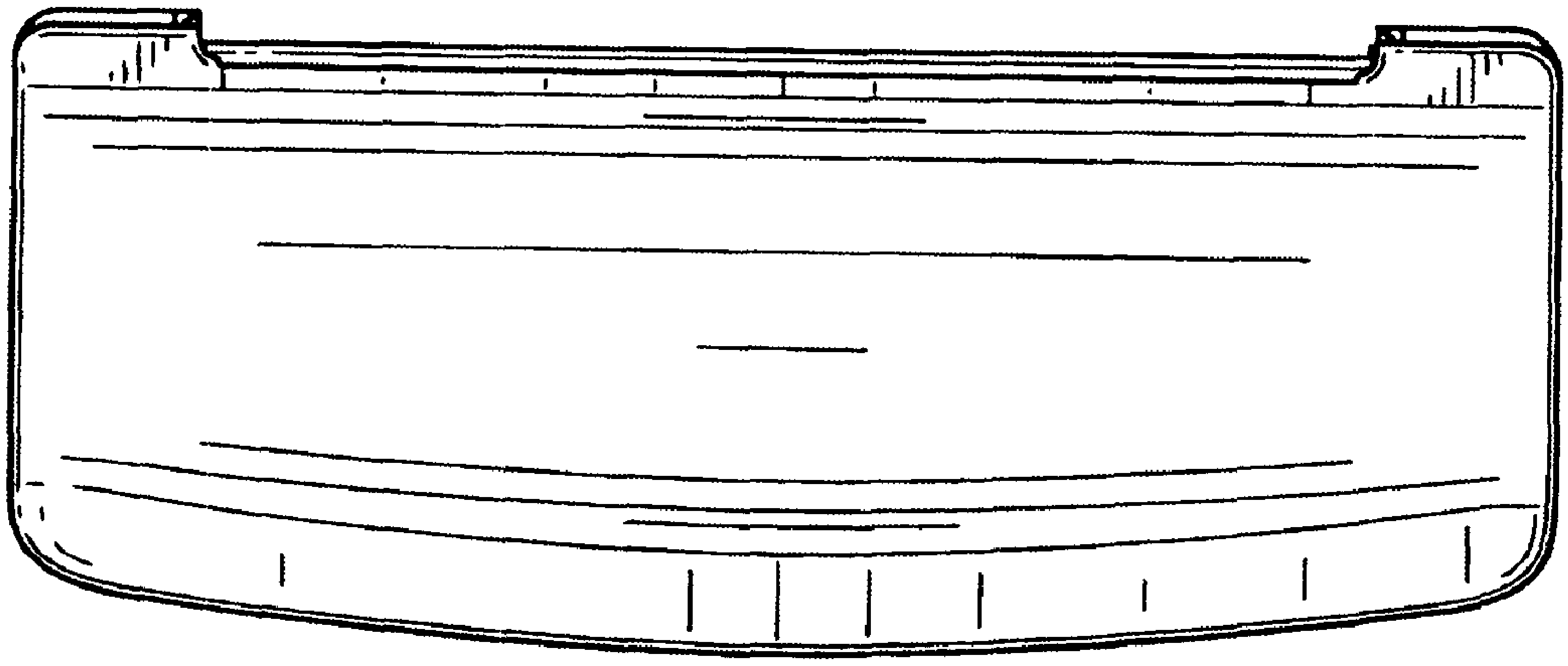


FIG. 15

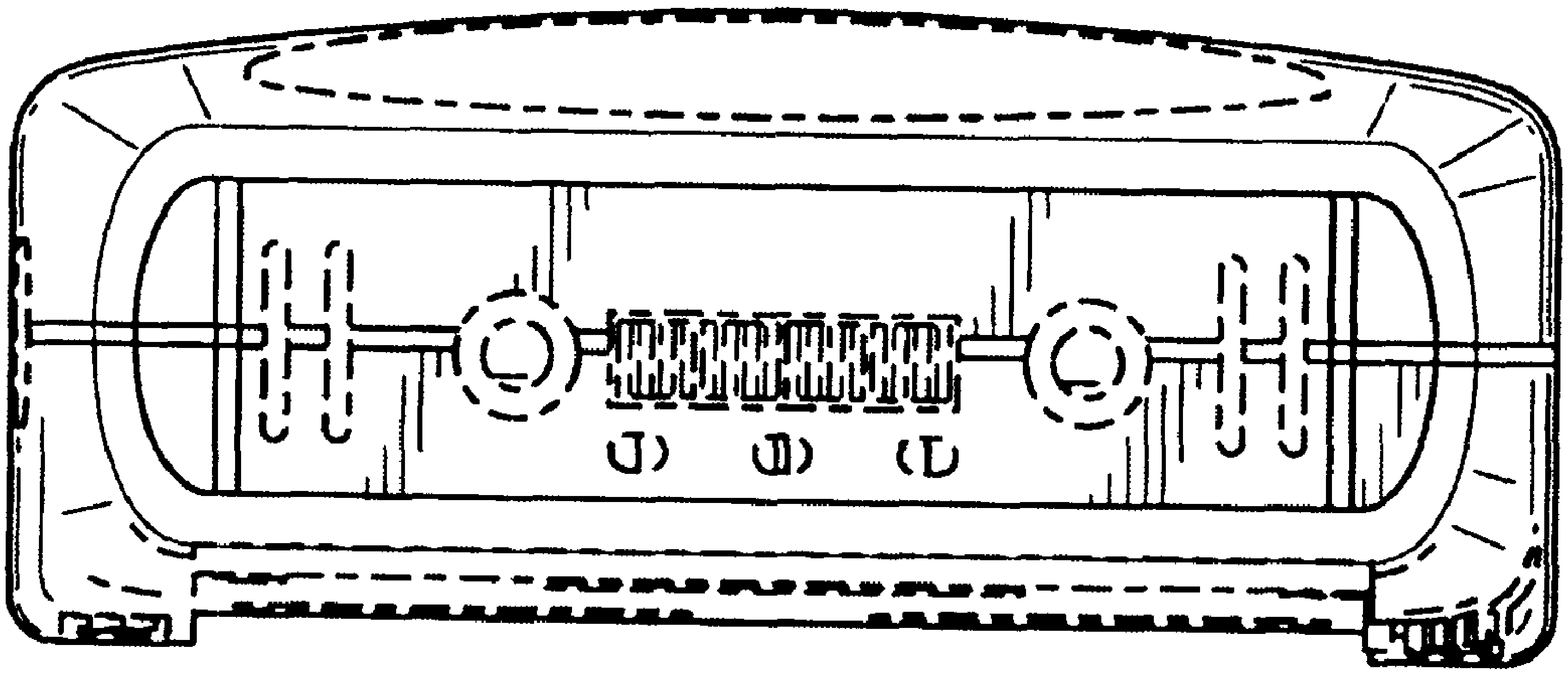


FIG. 16

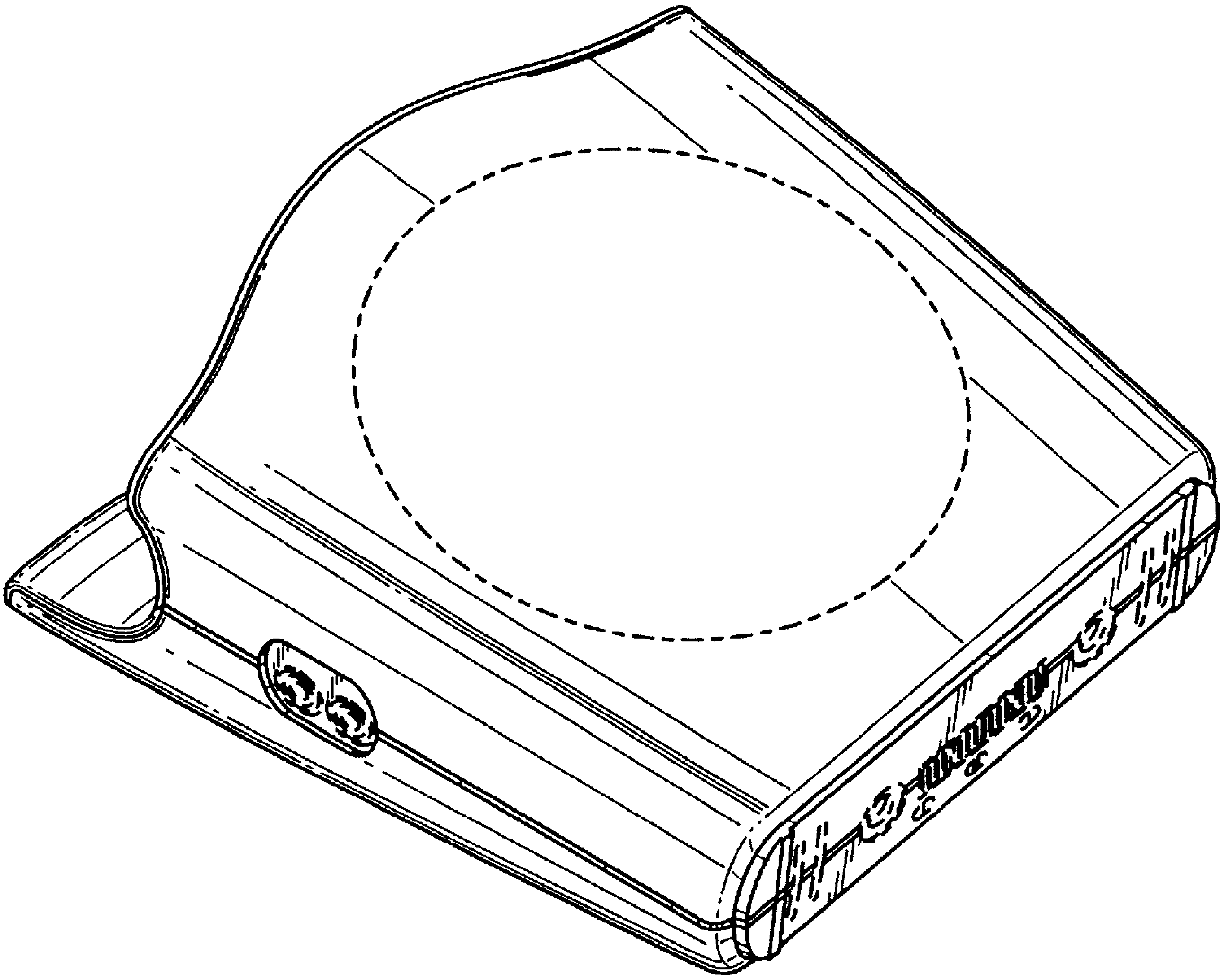


FIG. 17

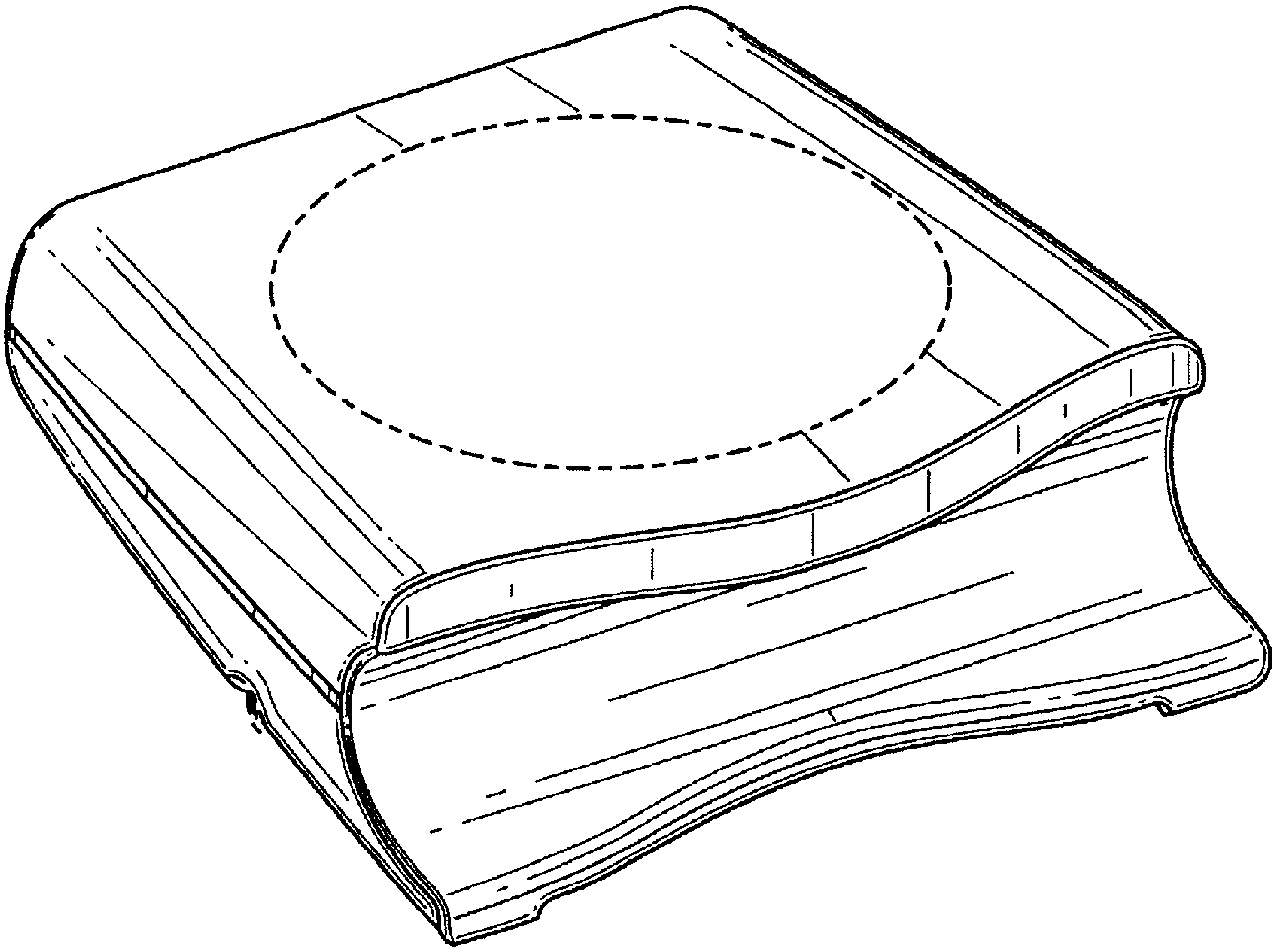


FIG. 18

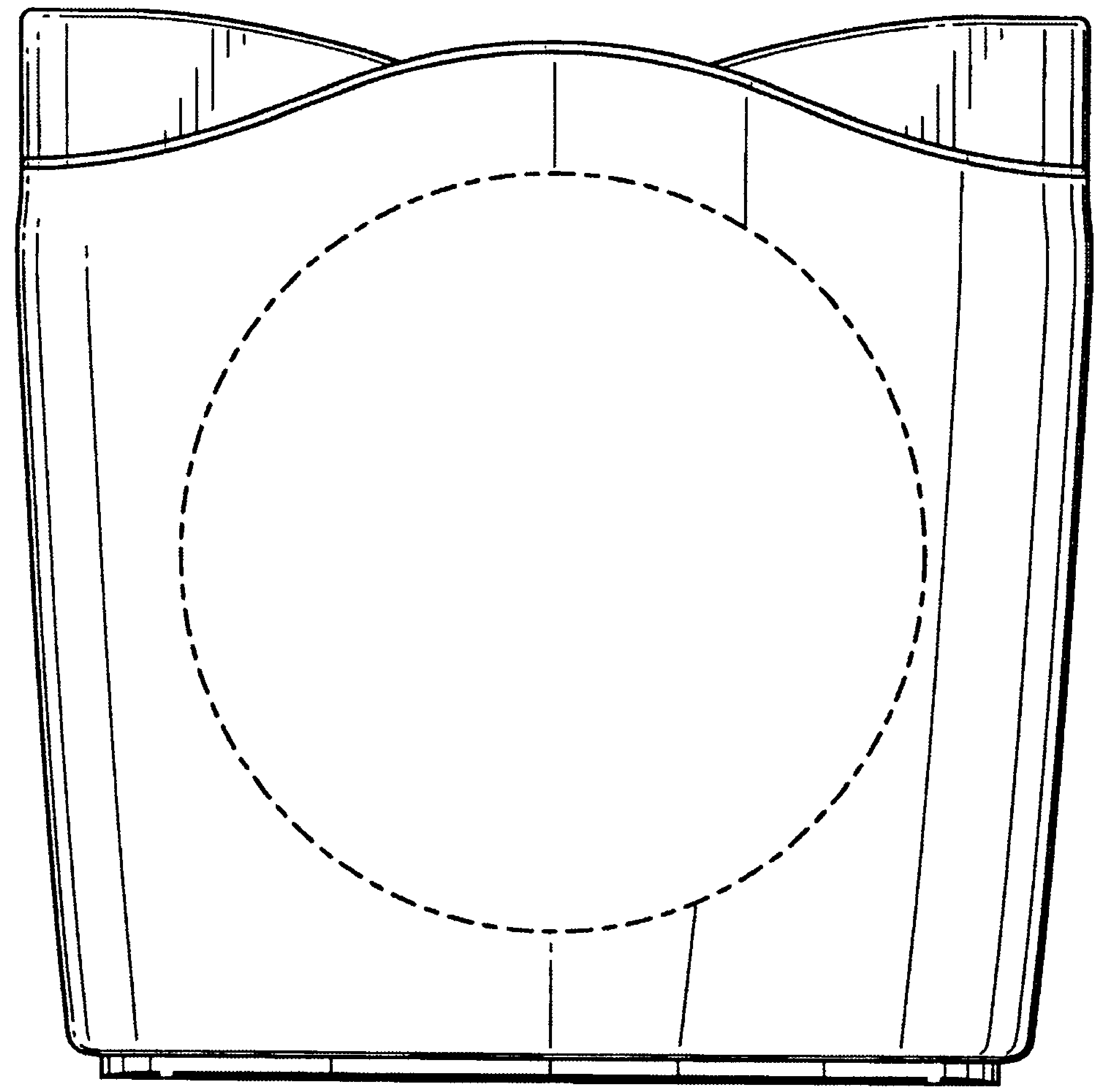


FIG. 19

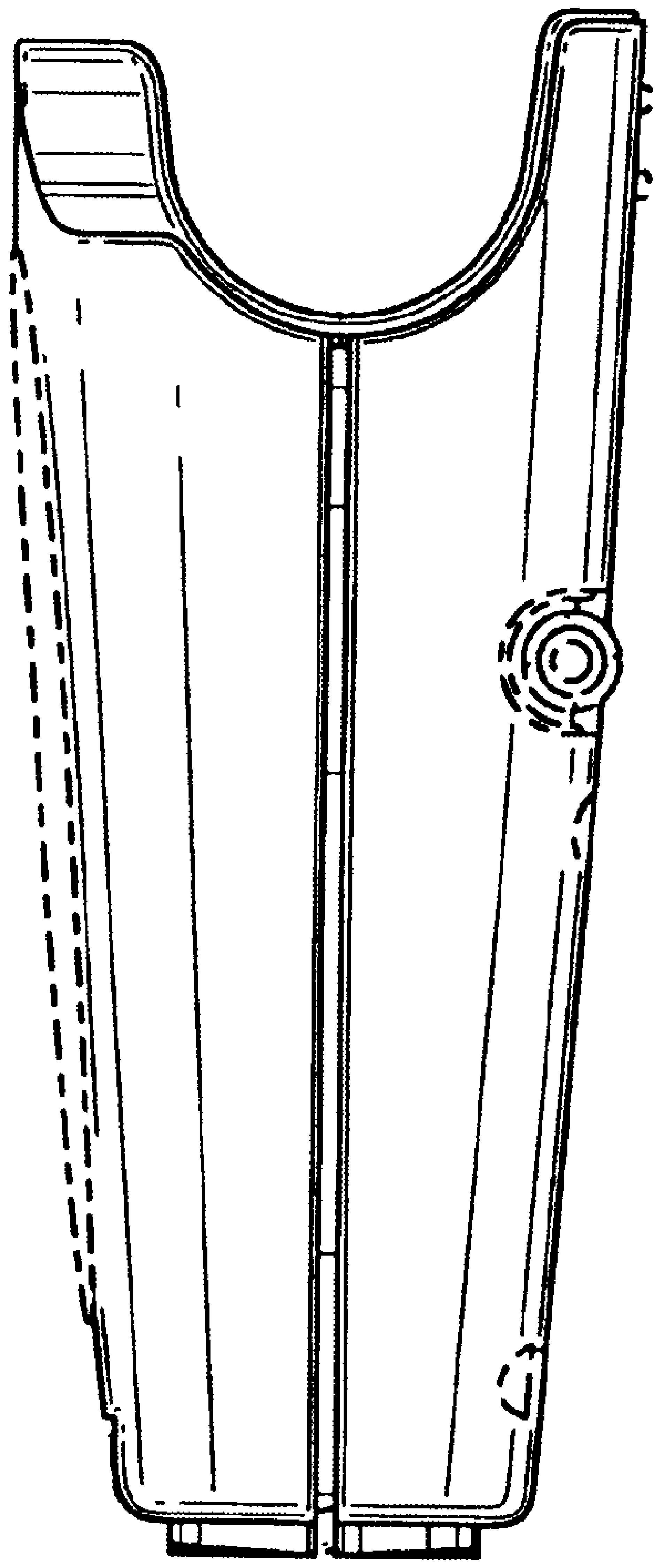


FIG. 20

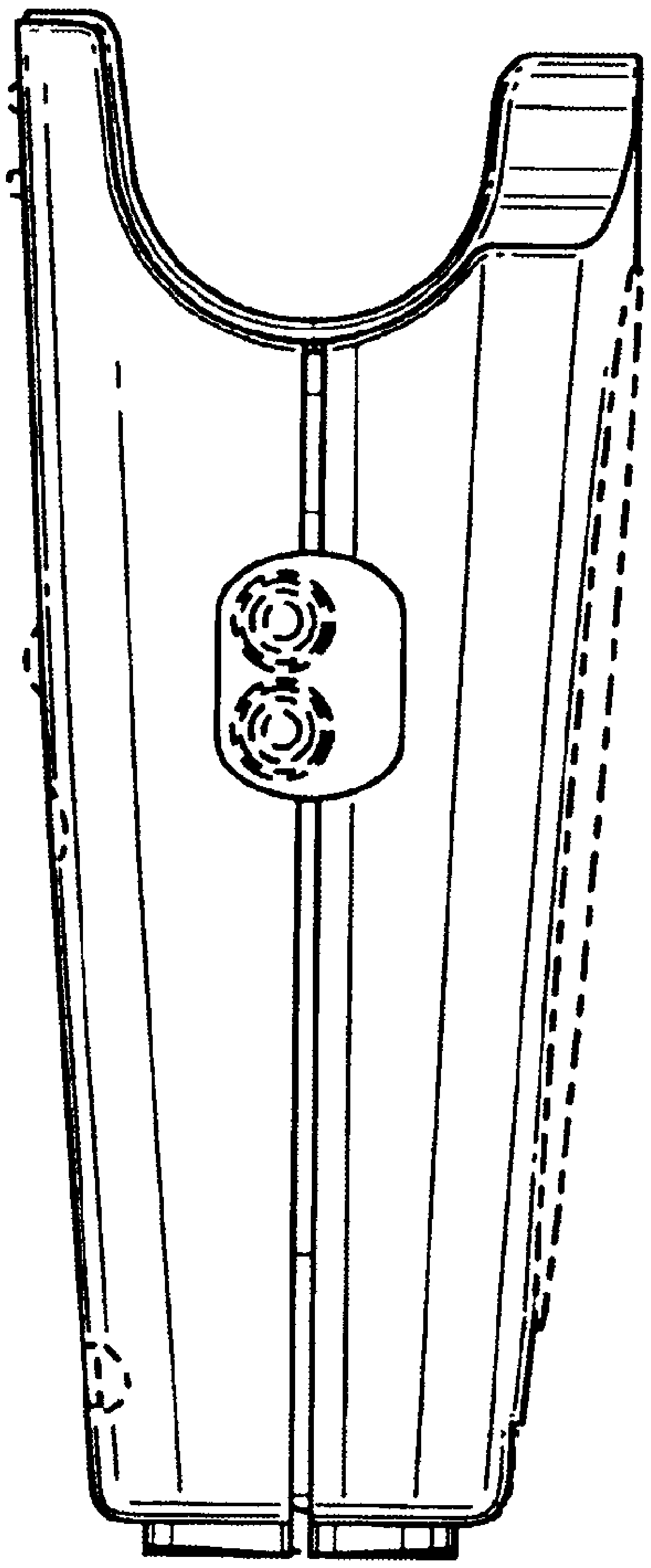


FIG. 21

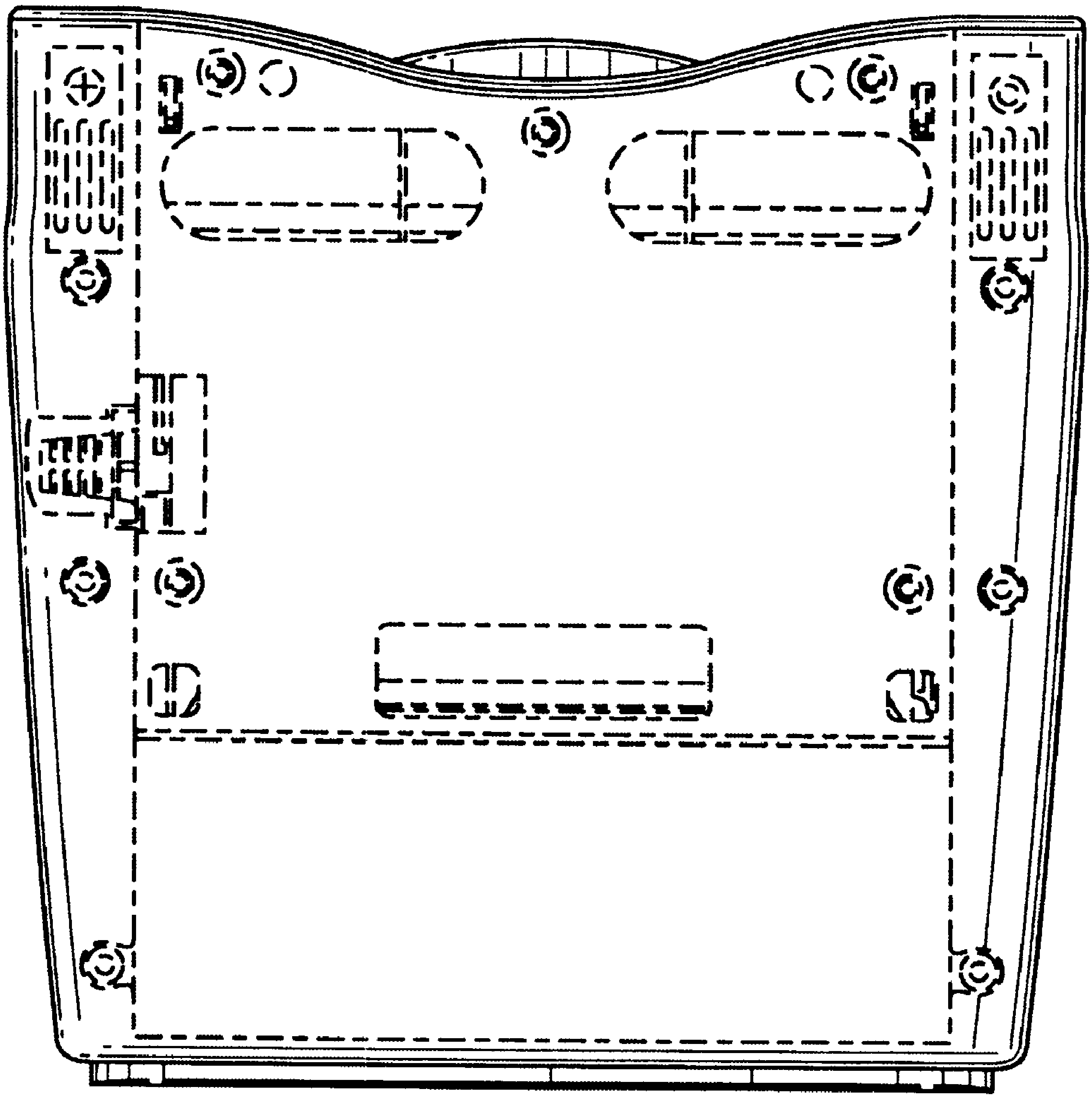
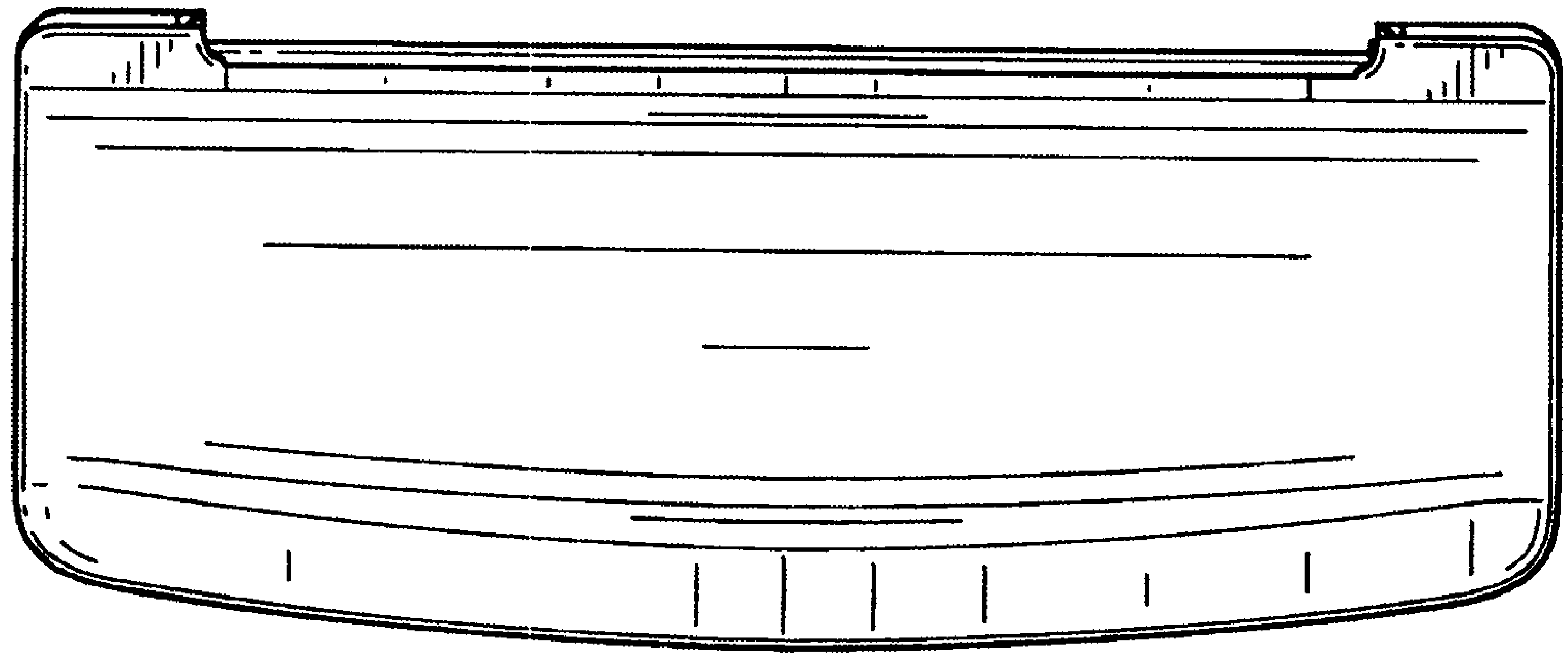


FIG. 22



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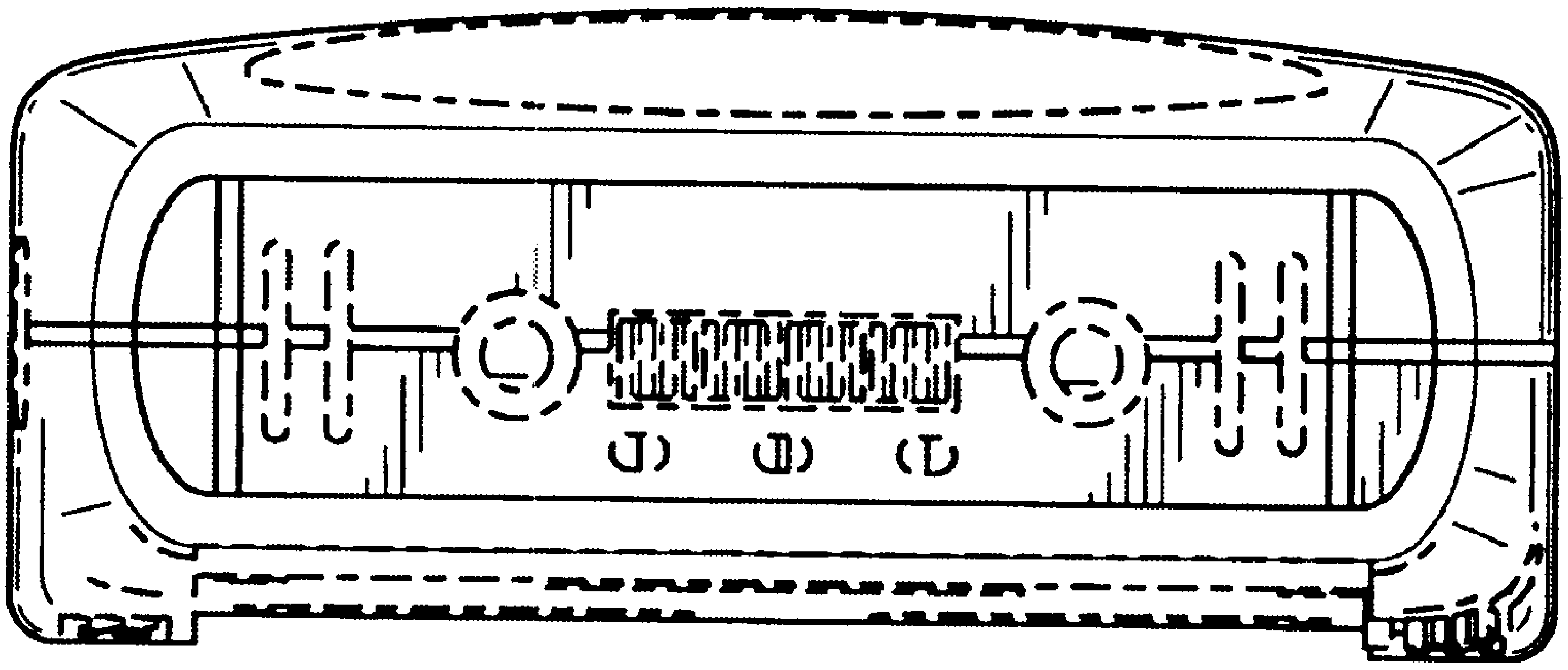

FIG. 24

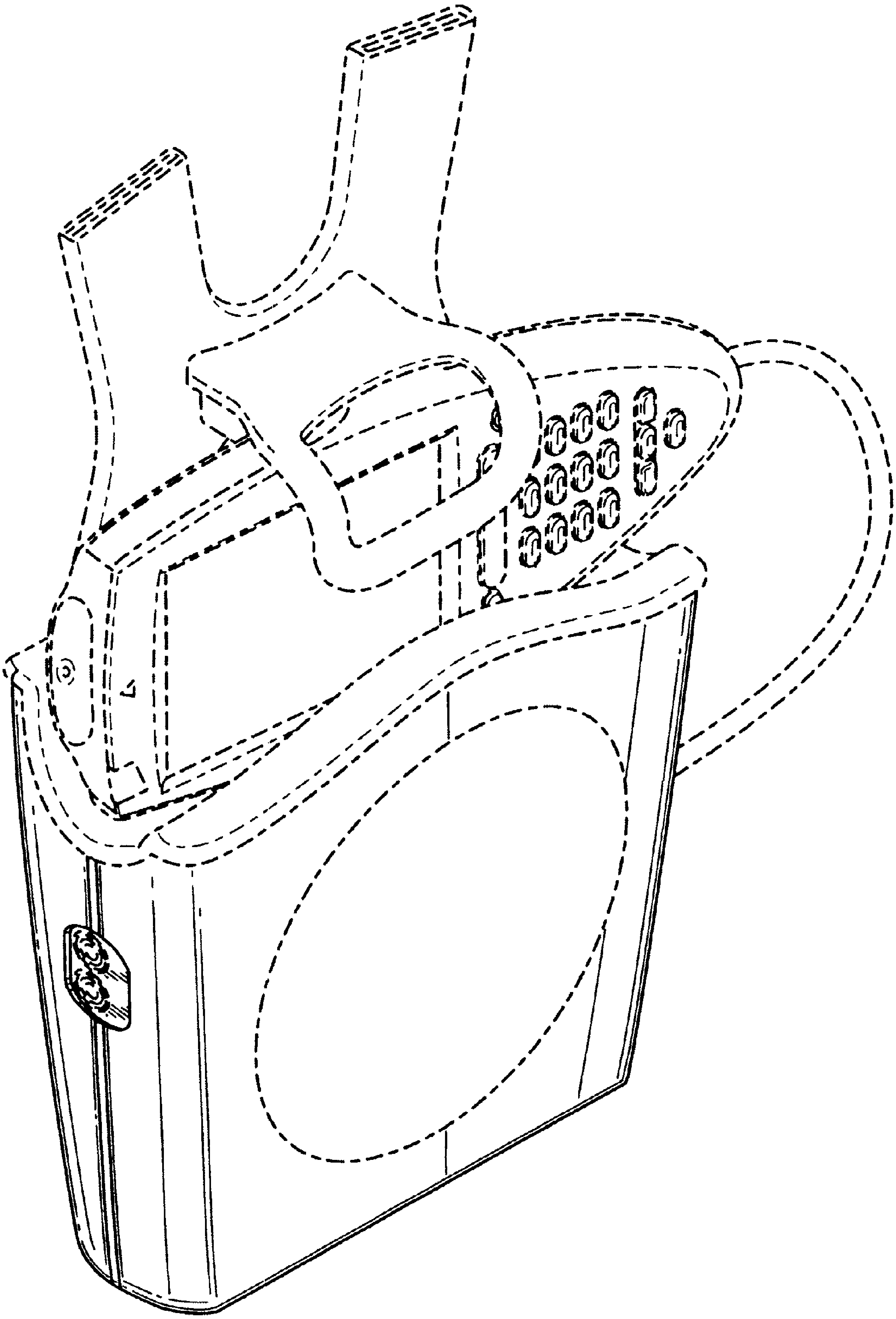

FIG. 25